

Description

The SX4407A uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$V_{DS} = -30V$ $I_D = -12A$

$R_{DS(ON)} < 13m\Omega$ @ $V_{GS} = -10V$

Application

Battery protection

Load switch

Uninterruptible power supply



Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-12	A
$I_D @ T_A = 70^\circ C$	Continuous Drain Current, $V_{GS} @ -10V^1$	-9.5	A
I_{DM}	Pulsed Drain Current ²	-50	A
EAS	Single Pulse Avalanche Energy ³	125	mJ
I_{AS}	Avalanche Current	-50	A
$P_D @ T_A = 25^\circ C$	Total Power Dissipation ⁴	1.5	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹	75	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance Junction-Ambient ¹ ($t \leq 10s$)	40	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	24	$^\circ C/W$

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_D=-250\mu\text{A}$	-30	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BVDSS Temperature Coefficient	Reference to 25°C , $\text{I}_D=-1\text{mA}$	---	-0.023	---	$\text{V}/^\circ\text{C}$
$\text{R}_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$\text{V}_{\text{GS}}=-10\text{V}$, $\text{I}_D=-10\text{A}$	---	10	13	$\text{m}\Omega$
		$\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_D=-10\text{A}$	---	16	20	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage		-1.0	-1.6	-2.5	V
$\Delta \text{V}_{\text{GS(th)}}$	$\text{V}_{\text{GS(th)}}$ Temperature Coefficient	$\text{V}_{\text{GS}}=\text{V}_{\text{DS}}$, $\text{I}_D=-250\mu\text{A}$	---	4.6	---	$\text{mV}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$\text{V}_{\text{DS}}=-24\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	-1	uA
		$\text{V}_{\text{DS}}=-24\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $T_J=55^\circ\text{C}$	---	---	-5	
I_{GSS}	Gate-Source Leakage Current	$\text{V}_{\text{GS}}=\pm 20\text{V}$, $\text{V}_{\text{DS}}=0\text{V}$	---	---	± 100	nA
g_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=-5\text{V}$, $\text{I}_D=-10\text{A}$	---	24	---	S
R_{g}	Gate Resistance	$\text{V}_{\text{DS}}=0\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	9	---	Ω
Q_{g}	Total Gate Charge (-4.5V)		---	20	---	nC
Q_{gs}	Gate-Source Charge	$\text{V}_{\text{DS}}=-15\text{V}$, $\text{V}_{\text{GS}}=-4.5\text{V}$, $\text{I}_D=-10\text{A}$	---	5.1	---	
Q_{gd}	Gate-Drain Charge		---	7.3	---	
$\text{T}_{\text{d(on)}}$	Turn-On Delay Time		---	33.8	---	ns
T_{r}	Rise Time	$\text{V}_{\text{DD}}=-15\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $\text{R}_{\text{G}}=3.3\text{k}\Omega$, $\text{I}_D=-1\text{A}$	---	35.8	---	
$\text{T}_{\text{d(off)}}$	Turn-Off Delay Time		---	72.8	---	
T_{f}	Fall Time		---	10.6	---	
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=-15\text{V}$, $\text{V}_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	---	2215	---	pF
C_{oss}	Output Capacitance		---	310	---	
C_{rss}	Reverse Transfer Capacitance		---	237	---	
I_{s}	Continuous Source Current ^{1,5}	$\text{V}_{\text{G}}=\text{V}_{\text{D}}=0\text{V}$, Force Current	---	---	-11.5	A
I_{SM}	Pulsed Source Current ^{2,5}		---	---	-46	A
V_{SD}	Diode Forward Voltage ²	$\text{V}_{\text{GS}}=0\text{V}$, $\text{I}_S=-1\text{A}$, $T_J=25^\circ\text{C}$	---	---	-1	V

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $\text{V}_{\text{DD}}=-25\text{V}$, $\text{V}_{\text{GS}}=-10\text{V}$, $L=0.1\text{mH}$, $\text{I}_{\text{AS}}=-50\text{A}$
- 4.The power dissipation is limited by 150°C junction temperature
- 5.The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

Typical Characteristics

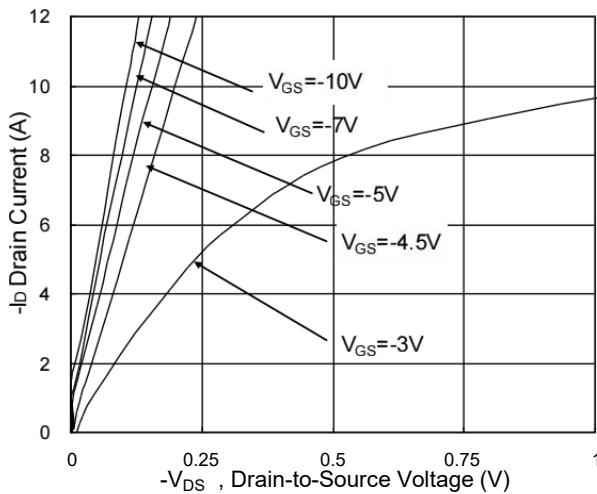


Fig.1 Typical Output Characteristics

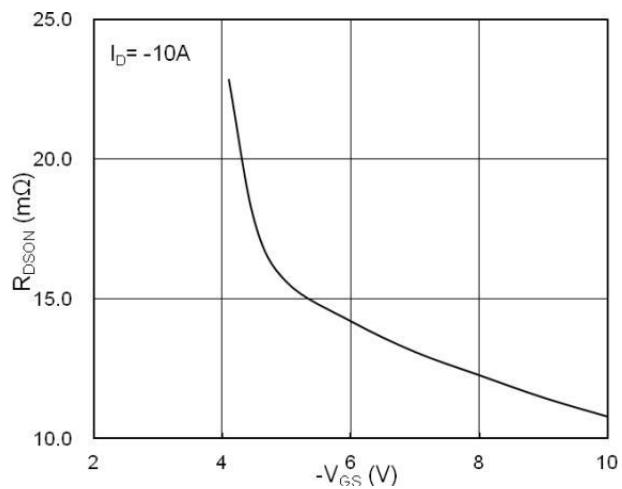


Fig.2 On-Resistance vs. G-S Voltage

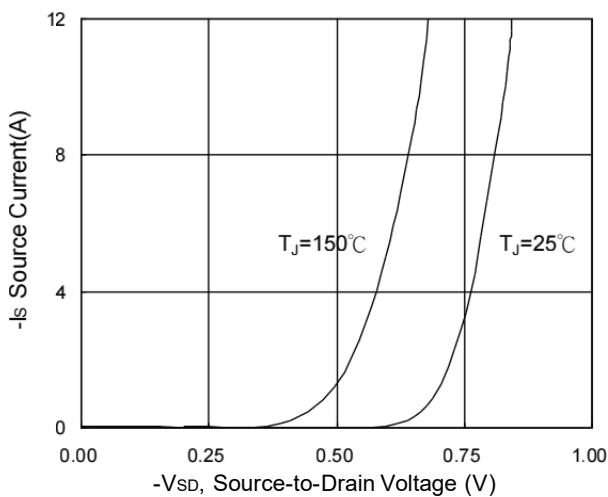


Fig.3 Forward Characteristics of Reverse

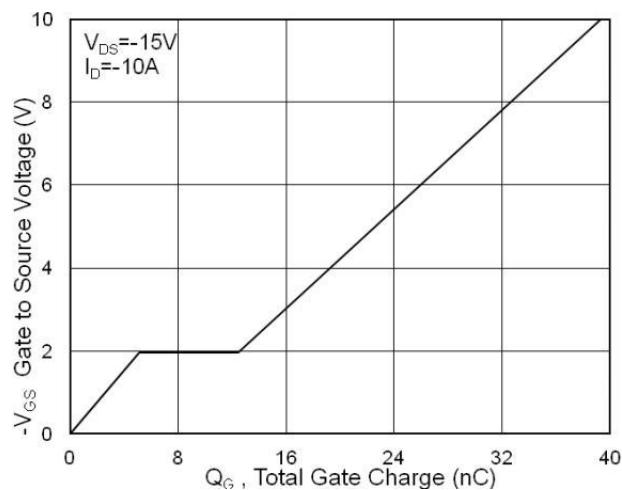


Fig.4 Gate-charge Characteristics

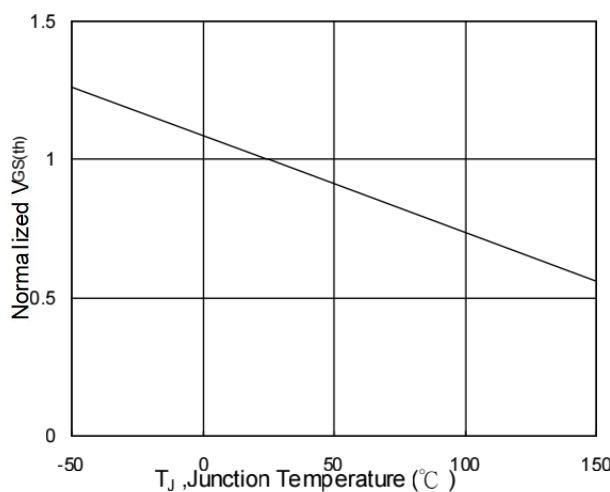


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

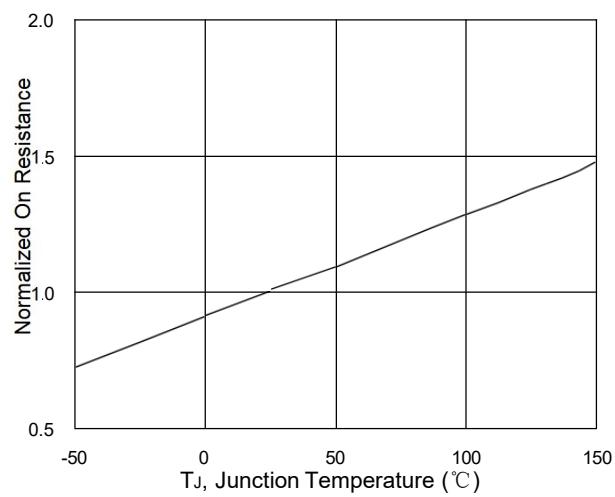


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

Typical Characteristics

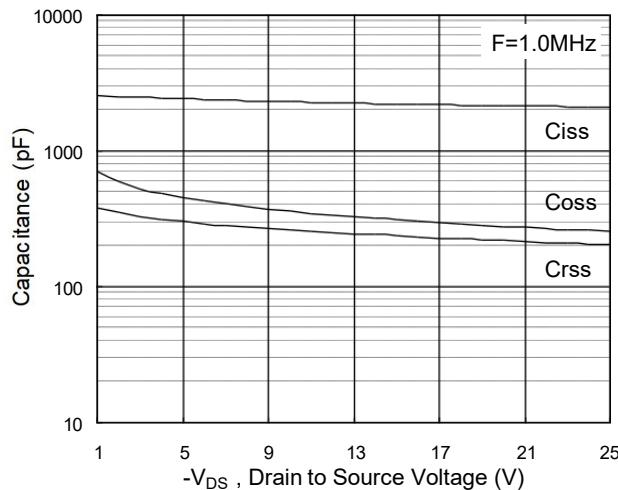


Fig.7 Capacitance

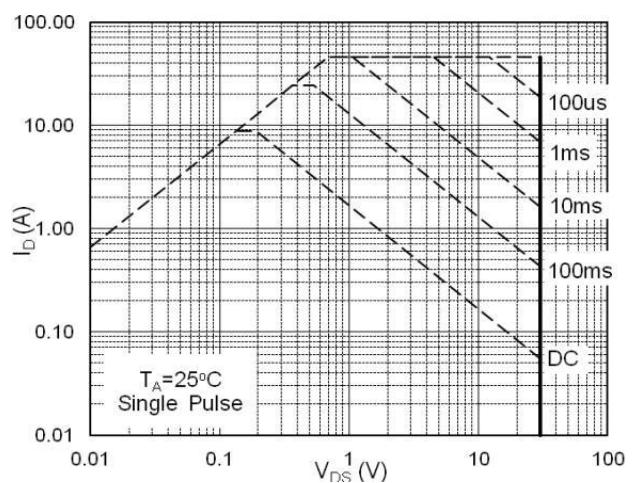


Fig.8 Safe Operating Area

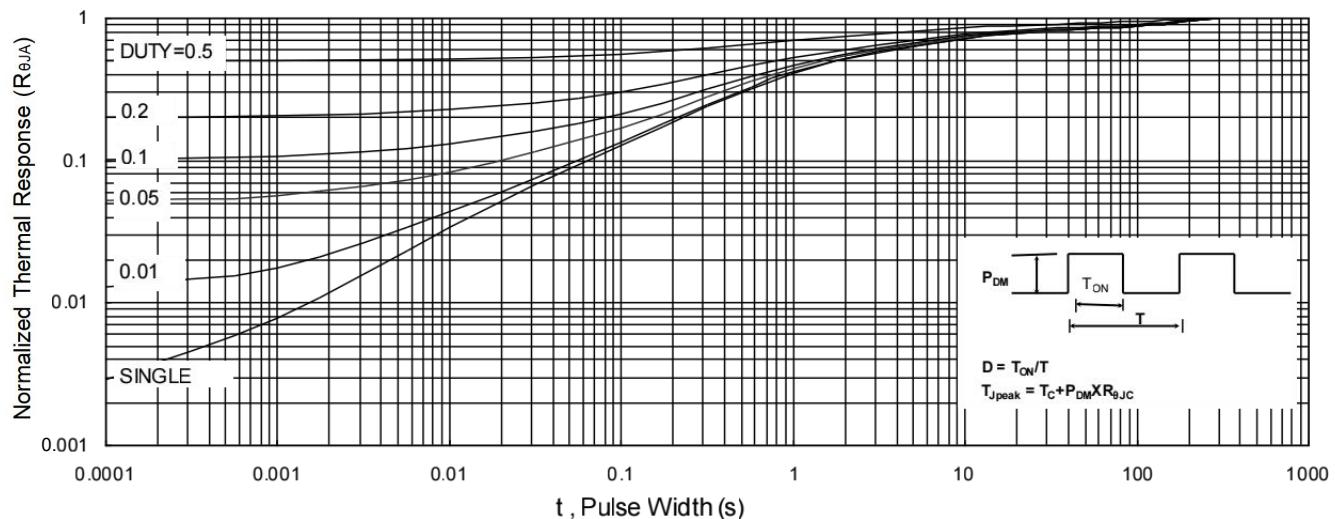


Fig.9 Normalized Maximum Transient Thermal Impedance

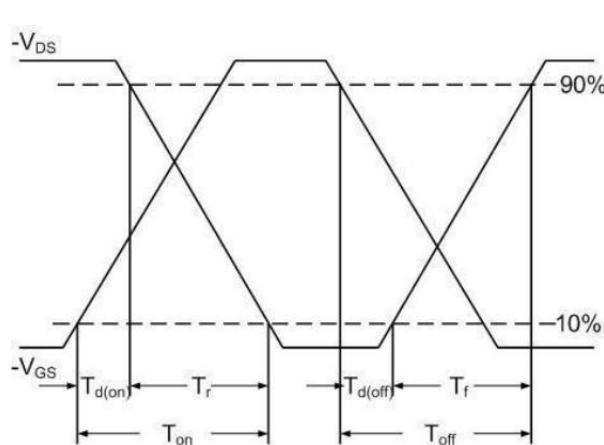


Fig.10 Switching Time Waveform

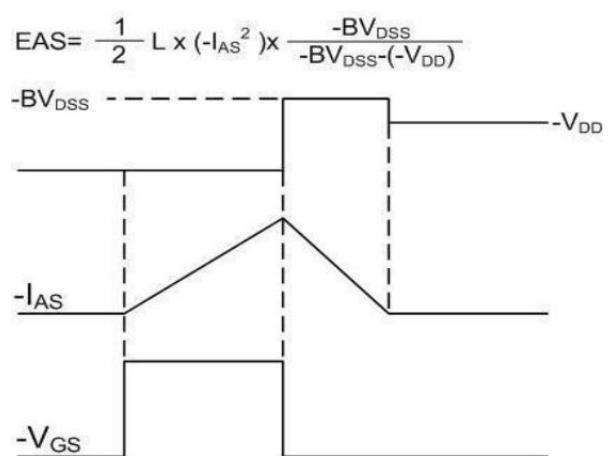
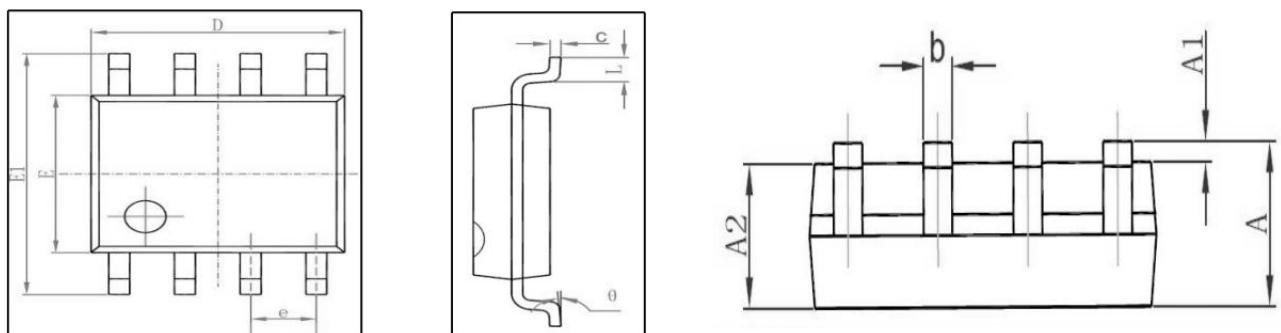
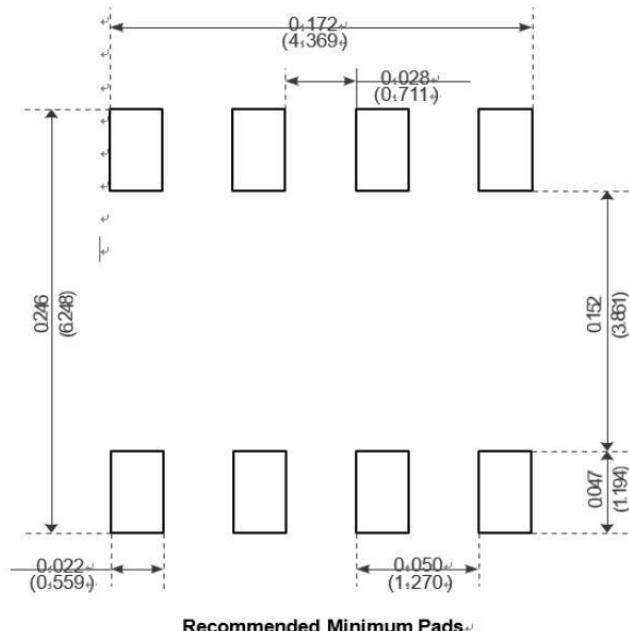


Fig.11 Unclamped Inductive Waveform

Package Mechanical Data-SOP-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270 (BSC)		0.050 (BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°



Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
TAPING	SOP-8		3000